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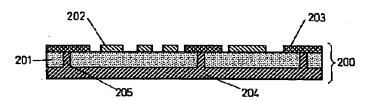
TITLE

CIRCUIT BOARD, MODULE

INCORPORATING CIRCUIT PART, AND

MANUFACTURING METHOD

THEREOF



ABSTRACT:

PROBLEM TO BE SOLVED: To provide a circuit board, together with its manufacturing method, for reduced processes and lower cost while a shield body shields electromagnetic wave and electrically connects to a ground pattern.

SOLUTION: A circuit board is provided which comprises an electric insulating board 201, a wiring pattern 202 and ground pattern 203 formed at least on one main surface or inside the electric insulating board, and a shield body 204 comprising conductive powder and thermosetting resin. Here, the shield body 204 is formed at least on one main surface or inside the electric insulating board 201, as well as in a through hole 205 provided at the electric insulating board. The ground pattern 203 and the shield body 204 are electrically connected.

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